Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2013-10-10
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	**Representative Title**	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	**Representative Email ***	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EBE3*VA16AAJ	A	ZY1A	2013-10-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	28.155	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3X3X0.86	8	gull wing	
Comment	Package: MSOP/TSSOP 8 BODY3.00 PITCH0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList :REACH-20th June 2013	
Query	**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**EBE3*VA16AAJ**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
SILICON DIE	Other inorganic materials	1.653	mg	supplier	DIE	Silicon (Si)	7440-21-3		1.626	mg	983666	57752
SILICON DIE			mg	supplier	METALLIZATION	Aluminium (Al)	7429-90-5		0.005	mg	3025	178
SILICON DIE			mg	supplier	METALLIZATION	Titanium (Ti)	7440-32-6		0.002	mg	1210	71
SILICON DIE			mg	supplier	METALLIZATION	Tungsten (W)	7440-33-7		0.001	mg	605	36
SILICON DIE			mg	supplier	PASSIVATION	Silicon Nitride (SiN)	68034-42-4		0.002	mg	1210	71
SILICON DIE			mg	supplier	PASSIVATION	Silicon Oxide(SiO2)	7631-86-9		0.011	mg	6655	391
SILICON DIE			mg	supplier	PASSIVATION	Gamma-butyrolactone	96-48-0		0.004	mg	2420	142
SILICON DIE			mg	supplier	PASSIVATION	Polyhydroxyamide	55295-98-2		0.002	mg	1210	71
LEADFRAME	Copper and its alloy	10.507	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		9.908	mg	942990	351909
LEADFRAME			mg	supplier	ALLOY	Nickel (Ni)	7440-02-0		0.309	mg	29409	10975
LEADFRAME			mg	supplier	ALLOY	Silicon (Si)	7440-21-3		0.067	mg	6377	2380
LEADFRAME			mg	supplier	ALLOY	Magnesium (Mg)	7439-95-4		0.015	mg	1428	533
LEADFRAME			mg	supplier	COATING	Nickel (Ni)	7440-02-0		0.203	mg	19320	7210
LEADFRAME			mg	supplier	COATING	Palladium (Pd)	7440-05-3		0.004	mg	381	142
LEADFRAME			mg	supplier	COATING	Gold (Au)	7440-57-5		0.001	mg	95	36
DIE ATTACH	Other organic materials	0.257	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0.018	mg	70039	639
DIE ATTACH			mg	supplier	GLUE	Epoxy resin B	68475-94-5		0.01	mg	38911	355
DIE ATTACH			mg	supplier	GLUE	Silver(Ag)	7440-22-4		0.199	mg	774319	7068
DIE ATTACH			mg	supplier	GLUE	Lactone	96-48-0		0.01	mg	38911	355
DIE ATTACH			mg	supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0.01	mg	38911	355
BONDING WIRE	Other inorganic materials	0.08	mg	supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	EC 417-470-1		0.01	mg	38911	355
BONDING WIRE			mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.079	mg	987500	2806
ENCAPSULATION	Other inorganic materials	15.658	mg	supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.001	mg	12500	36
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		1.495	mg	95478	53099
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		12.951	mg	827117	459989
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		1.08	mg	68974	38359
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.083	mg	5301	2948
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Bismuth (Bi)	7440-69-9		0.049	mg	3129	1740